

PESD12VS1ULD

Unidirectional ESD protection diode

Rev. 1 — 11 May 2011

Product data sheet

1. Product profile

1.1 General description

Unidirectional ElectroStatic Discharge (ESD) protection diode designed to protect one signal line from the damage caused by ESD and other transients. The device is housed in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- ESD protection of one line
- Ultra small SMD plastic package
- Solderable side pads
- Package height typ. 0.37 mm
- Low clamping voltage: $V_{CL} = 19\text{ V}$
- AEC-Q101 qualified
- ESD protection up to 30 kV
- IEC 61000-4-2; level 4 (ESD)
- IEC 61000-4-5 (surge); $I_{PP} = 5\text{ A}$
- Max. peak pulse power: $P_{PP} = 150\text{ W}$
- Ultra low leakage current: $I_{RM} < 1\text{ nA}$

1.3 Applications

- Computers and peripherals
- Audio and video equipment
- Communication systems
- Portable electronics

1.4 Quick reference data

Table 1. Quick reference data

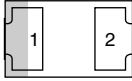
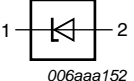
$T_{amb} = 25\text{ °C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|--------------------------|--------------------------------------|-----|-----|-----|------|
| V_{RWM} | reverse standoff voltage | | - | - | 12 | V |
| C_d | diode capacitance | $f = 1\text{ MHz}; V_R = 0\text{ V}$ | - | 38 | 75 | pF |



2. Pinning information

Table 2. Pinning

| Pin | Description | Simplified outline | Graphic symbol |
|-----|-----------------------------|--|---|
| 1 | cathode [1] |  <p>Transparent top view</p> |  |
| 2 | anode | | |

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|--------------|---------|--|---------|
| | Name | Description | Version |
| PESD12VS1ULD | - | leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm | SOD882D |

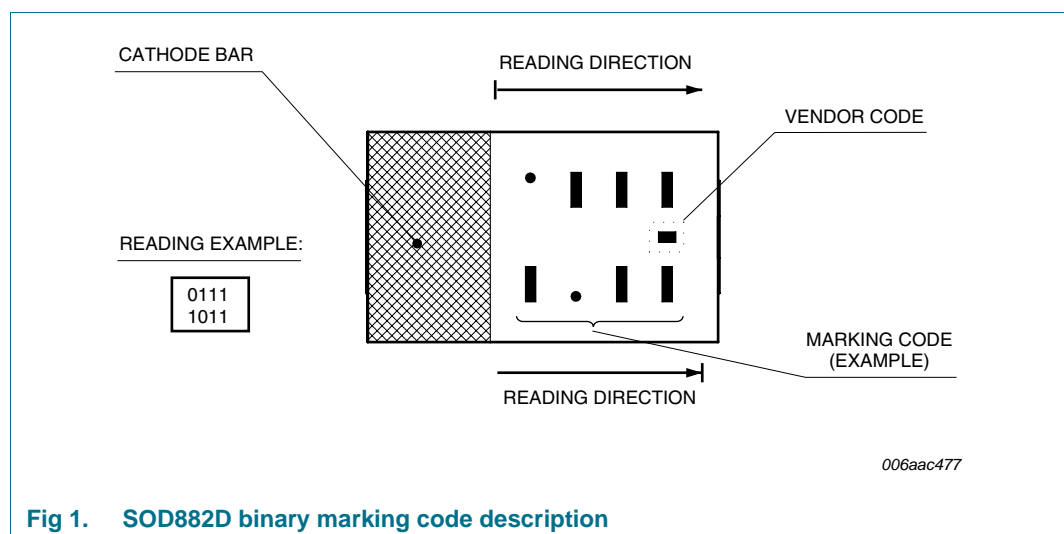
4. Marking

Table 4. Marking codes

| Type number | Marking code [1] |
|--------------|----------------------------------|
| PESD12VS1ULD | 1010 0000 |

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|----------------------|--------------------|-------|------|------|
| P_{PP} | peak pulse power | $t_p = 8/20 \mu s$ | [1] - | 150 | W |
| I_{PP} | peak pulse current | $t_p = 8/20 \mu s$ | [1] - | 5 | A |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -55 | +150 | °C |
| T_{stg} | storage temperature | | -65 | +150 | °C |

[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

Table 6. ESD maximum ratings

$T_{amb} = 25 \text{ }^\circ\text{C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------------------|-----------------------------------|----------|-----|------|
| V_{ESD} | electrostatic discharge voltage | IEC 61000-4-2 (contact discharge) | [1][2] - | 30 | kV |
| | | MIL-STD-883 (human body model) | [2] - | 10 | kV |

[1] Device stressed with ten non-repetitive ESD pulses.

[2] Measured from pin 1 to 2.

Table 7. ESD standards compliance

| Standard | Conditions |
|---|---------------------------------|
| IEC 61000-4-2; level 4 (ESD) | > 15 kV (air); > 8 kV (contact) |
| MIL-STD-883; class 3 (human body model) | > 4 kV |

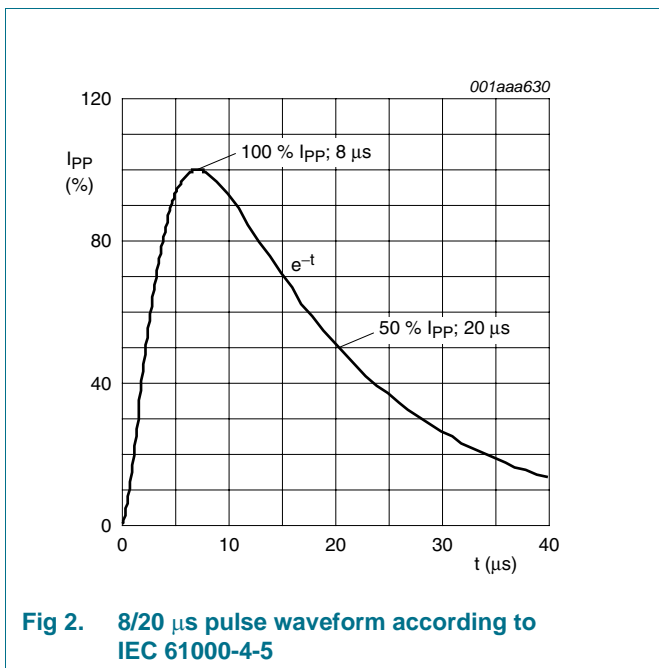


Fig 2. 8/20 μs pulse waveform according to IEC 61000-4-5

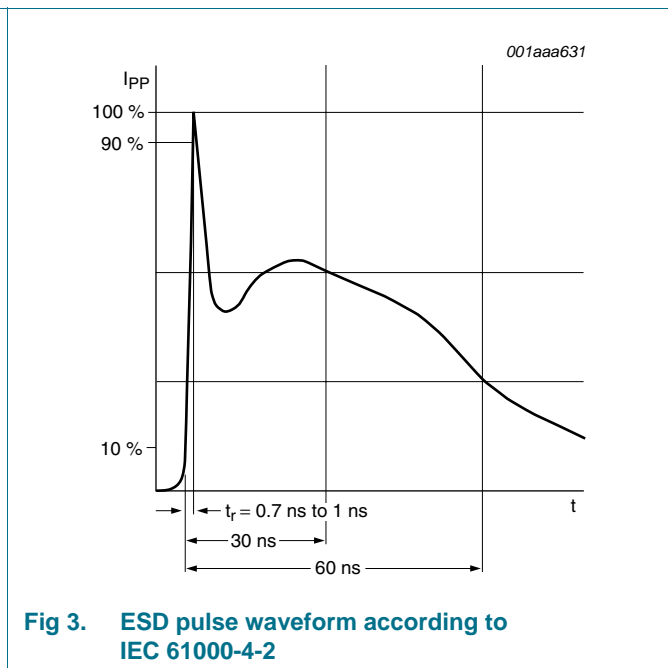


Fig 3. ESD pulse waveform according to IEC 61000-4-2

6. Characteristics

Table 8. Characteristics

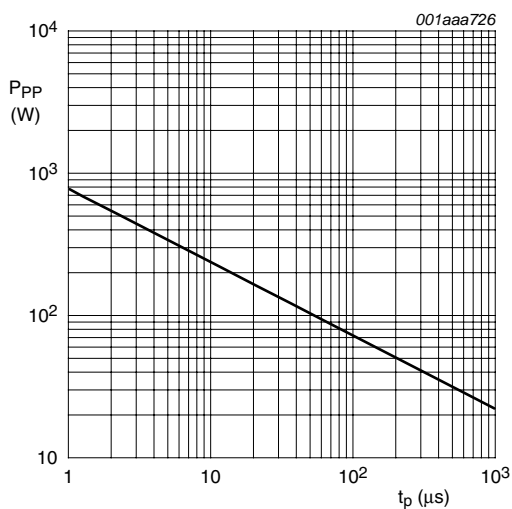
$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|--------------------------|--------------------------------------|--------|-----|------|----------|
| V_{RWM} | reverse standoff voltage | | - | - | 12 | V |
| I_{RM} | reverse leakage current | $V_{RWM} = 12\text{ V}$ | - | < 1 | 50 | nA |
| V_{BR} | breakdown voltage | $I_R = 5\text{ mA}$ | 14.7 | 15 | 15.3 | V |
| C_d | diode capacitance | $f = 1\text{ MHz}; V_R = 0\text{ V}$ | - | 38 | 75 | pF |
| V_{CL} | clamping voltage | | [1][2] | | | |
| | | $I_{PP} = 1\text{ A}$ | - | - | 19 | V |
| | | $I_{PP} = 5\text{ A}$ | - | - | 35 | V |
| r_{dyn} | dynamic resistance | $I_R = 10\text{ A}$ | [3] | - | 0.6 | Ω |

[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[2] Measured from pin 1 to 2.

[3] Non-repetitive current pulse, Transmission Line Pulse (TLP) $t_p = 100\text{ ns}$; square pulse; ANS/IESD STM5-1-2008.



$T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 4. Peak pulse power as a function of exponential pulse duration; typical values

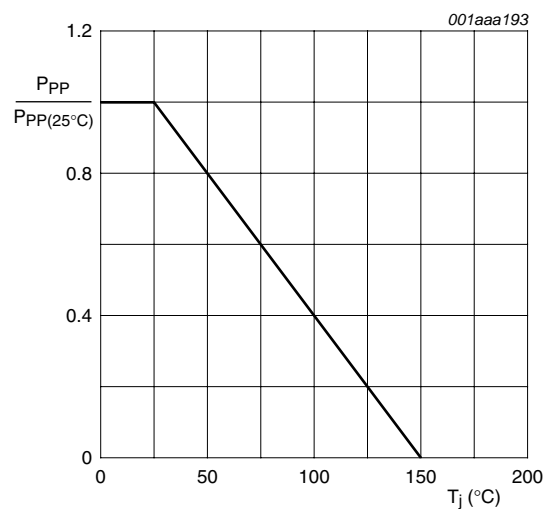
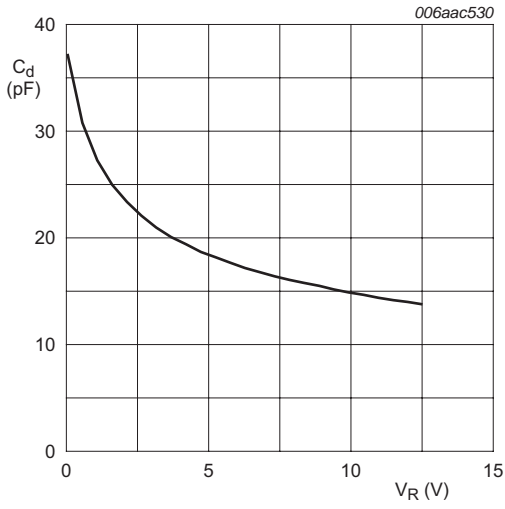


Fig 5. Relative variation of peak pulse power as a function of junction temperature; typical values



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

Fig 6. Diode capacitance as a function of reverse voltage; typical values

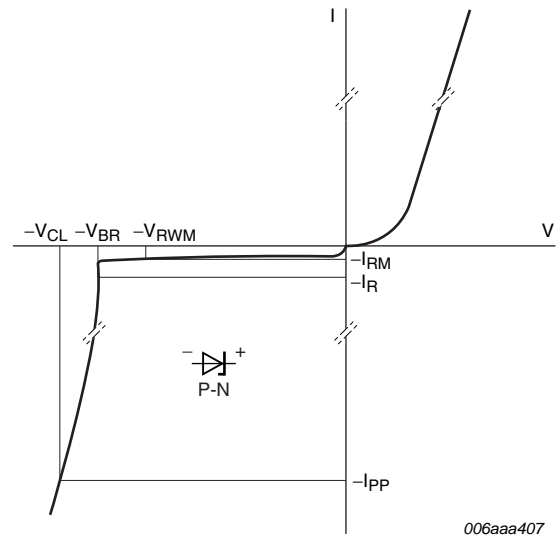


Fig 7. V-I characteristics for a unidirectional ESD protection diode

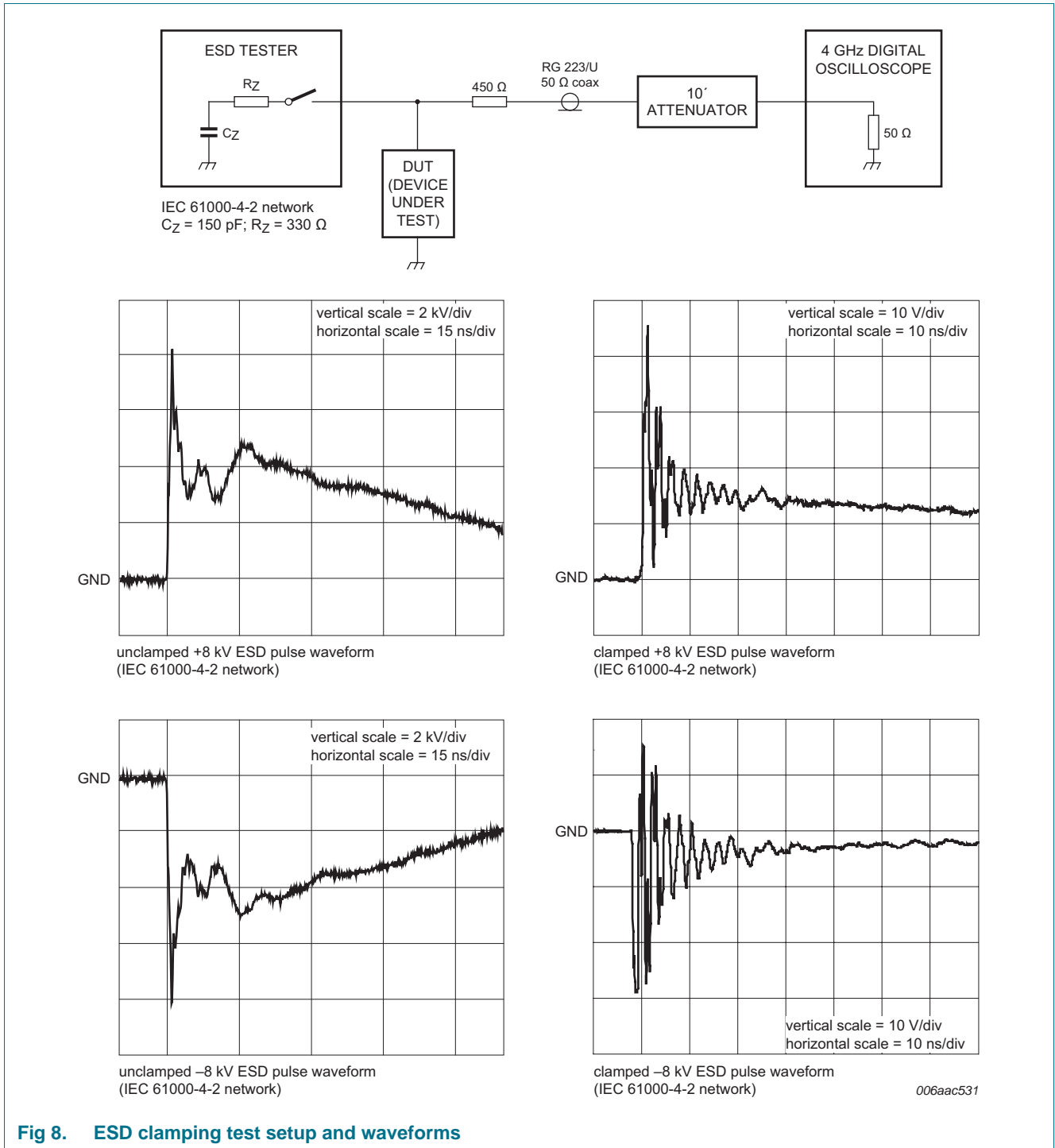


Fig 8. ESD clamping test setup and waveforms

7. Application information

The PESD12VS1ULD is designed for the protection of one unidirectional data or signal line from the damage caused by ESD and surge pulses. The device may be used on lines where the signal polarities are either positive or negative with respect to ground. The PESD12VS1ULD provides a surge capability of 150 W per line for an 8/20 μ s waveform.

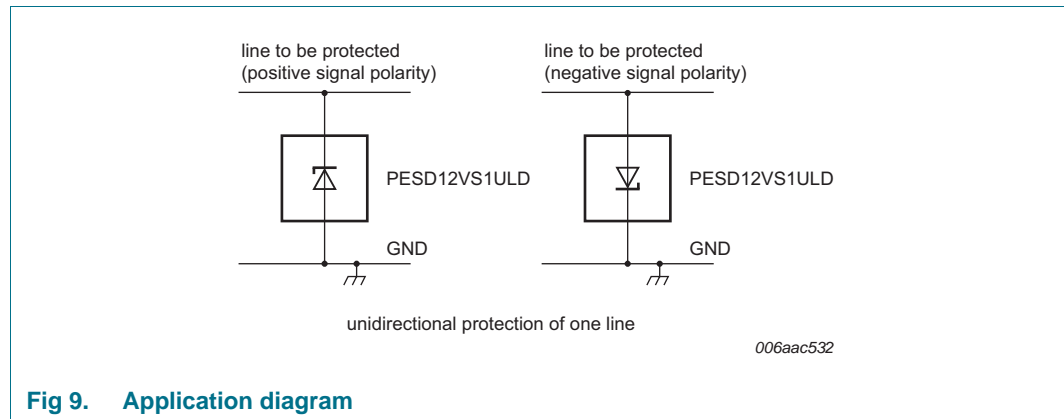


Fig 9. Application diagram

Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

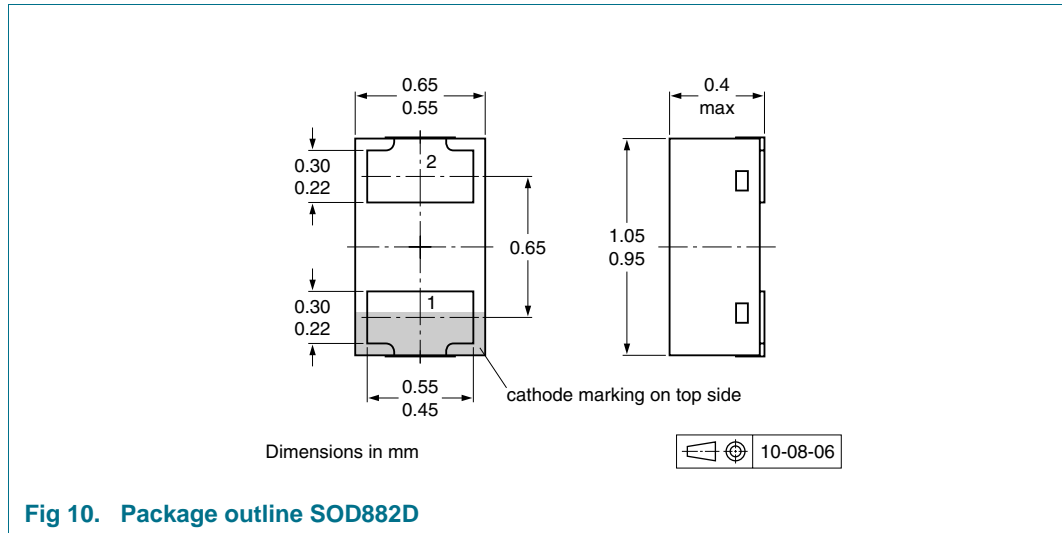
1. Place the PESD12VS1ULD as close to the input terminal or connector as possible.
2. The path length between the PESD12VS1ULD and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

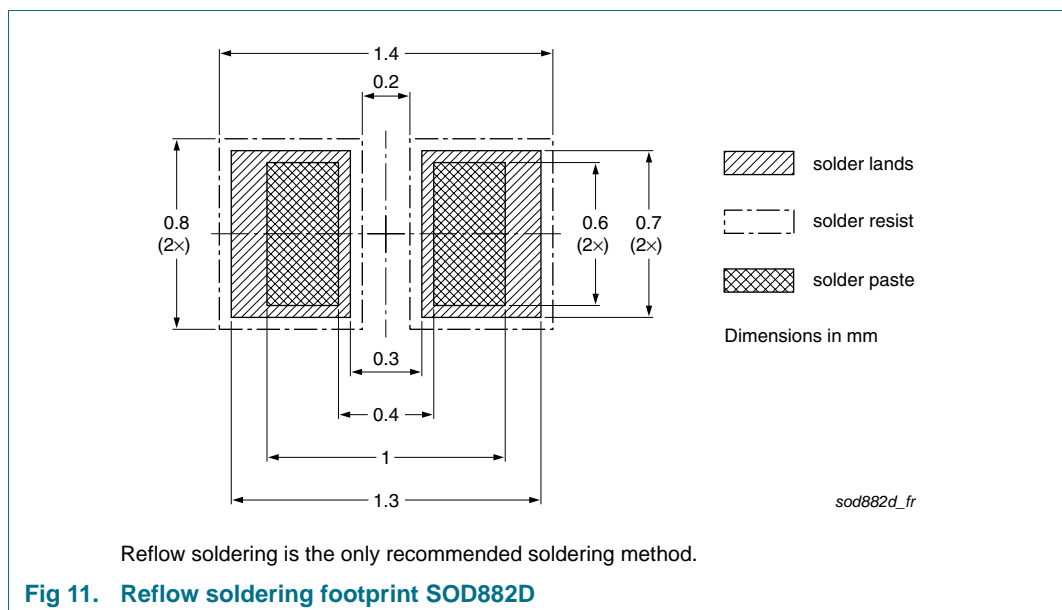
Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity |
|--------------|---------|--------------------------------|------------------|
| PESD12VS1ULD | SOD882D | 2 mm pitch, 8 mm tape and reel | 10000 -315 |

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 10. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|------------------|--------------|--------------------|---------------|------------|
| PESD12VS1ULD v.1 | 20110511 | Product data sheet | - | - |

13. Legal information

13.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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